

30V N-Channel Enhancement Mode MOSFET

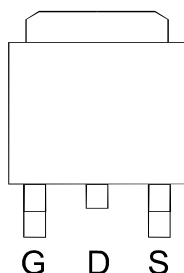
GENERAL DESCRIPTION

The ME70N03S is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits where high-side switching and low in-line power loss are needed in a very small outline surface mount package.

PIN CONFIGURATION

(TO-252)

Top View

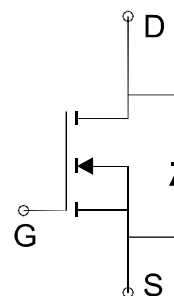


FEATURES

- $R_{DS(ON)} \leq 6.6m\Omega @ V_{GS}=10V$
- $R_{DS(ON)} \leq 11m\Omega @ V_{GS}=4.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability

APPLICATIONS

- Power Management in Note book
- Portable Equipment
- Battery Powered System
- DC/DC Converter
- Load Switch
- DSC



Ordering Information: ME70N03S (Pb-free)

ME70N03S-G (Green product-Halogen free)

Absolute Maximum Ratings (TA=25°C Unless Otherwise Noted)

Parameter	Symbol	Maximum Ratings	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current*	I_D	$T_C=25^\circ C$	62
		$T_C=70^\circ C$	50
		$T_A=25^\circ C$	17
		$T_A=70^\circ C$	13
Pulsed Drain Current	I_{DM}	248	A
Maximum Power Dissipation	P_D	$T_C=25^\circ C$	41
		$T_C=70^\circ C$	26
		$T_A=25^\circ C$	3.1
		$T_A=70^\circ C$	2
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to 150	$^\circ C$
Thermal Resistance-Junction to Case	$R_{\theta JC}$	3	$^\circ C/W$

*The device mounted on 1in² FR4 board with 2 oz copper



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Electrical Characteristics ($T_A=25^\circ\text{C}$ Unless Otherwise Specified)

Symbol	Parameter	Limit	Min	Typ	Max	Unit
STATIC						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	30			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1		3	V
I_{GSS}	Gate-Body Leakage	$V_{DS}=0V, V_{GS}=\pm 20V$			± 100	nA
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=30V, V_{GS}=0V$			1	μA
$R_{DS(on)}$	Drain-Source On-State Resistance ^a	$V_{GS}=10V, I_D=30A$		5.5	6.6	m Ω
		$V_{GS}=4.5V, I_D=15A$		8.5	11	
V_{SD}	Diode Forward Voltage	$I_S=20A, V_{GS}=0V$		0.85	1.2	V
DYNAMIC						
Q_g	Total Gate Charge	$V_{DS}=15V, V_{GS}=10V, I_D=25A$		38		nC
Q_g	Total Gate Charge	$V_{DS}=15V, V_{GS}=4.5V, I_D=25A$		19.5		
Q_{gs}	Gate-Source Charge			8		
Q_{gd}	Gate-Drain Charge			11		
C_{iss}	Input Capacitance	$V_{DS}=15V, V_{GS}=0V,$ $F=1MHz$		1620		pF
C_{oss}	Output Capacitance			255		
C_{rss}	Reverse Transfer Capacitance			80		
R_g	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1MHz$		1.1		Ω
$t_{d(on)}$	Turn-On Delay Time	$R_L=15\Omega, V_{GEN}=10V, I_D=1A$ $V_{DD}=15V, R_G=3\Omega$		17		ns
t_r	Turn-On Rise Time			15		
$t_{d(off)}$	Turn-Off Delay Time			58		
t_f	Turn-Off Fall Time			6		

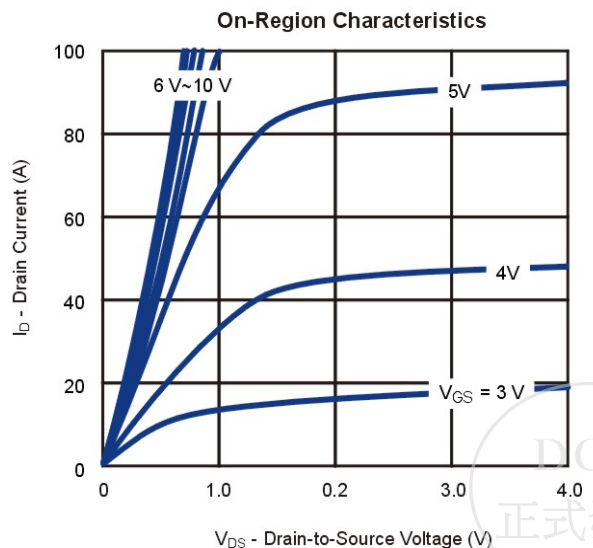
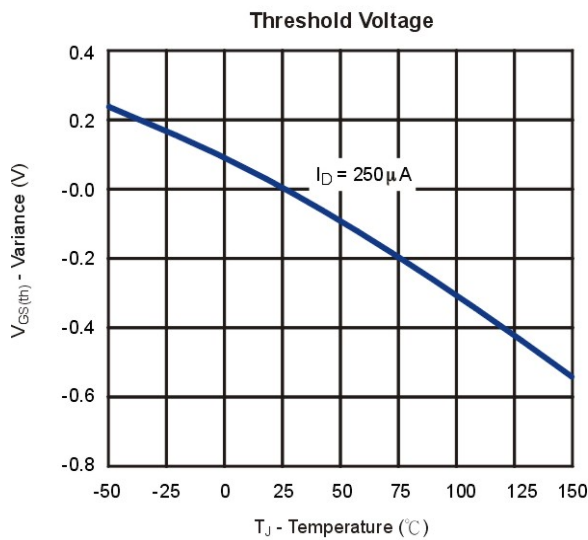
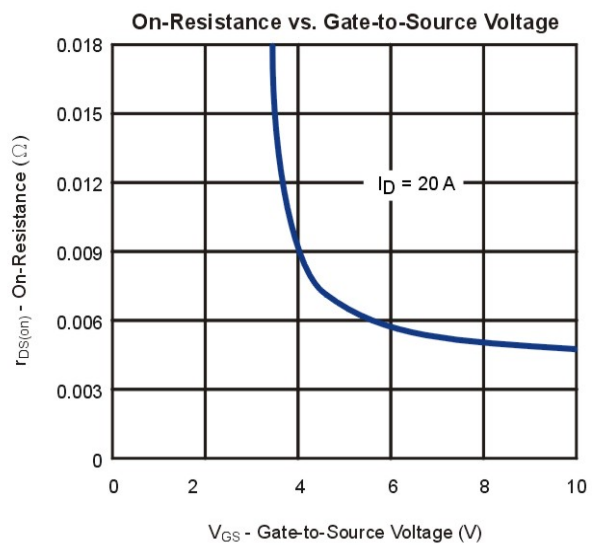
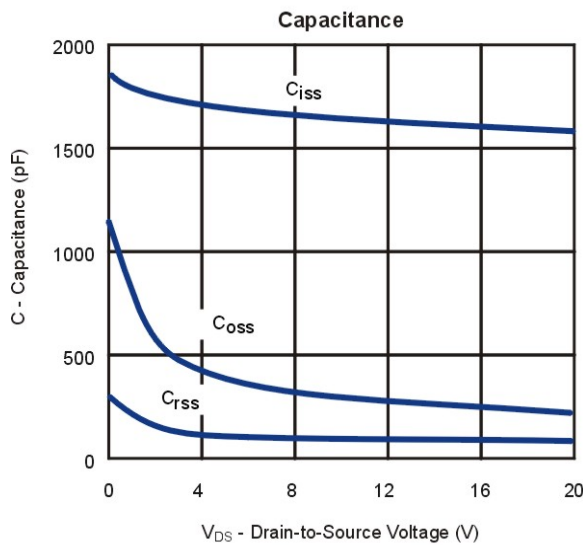
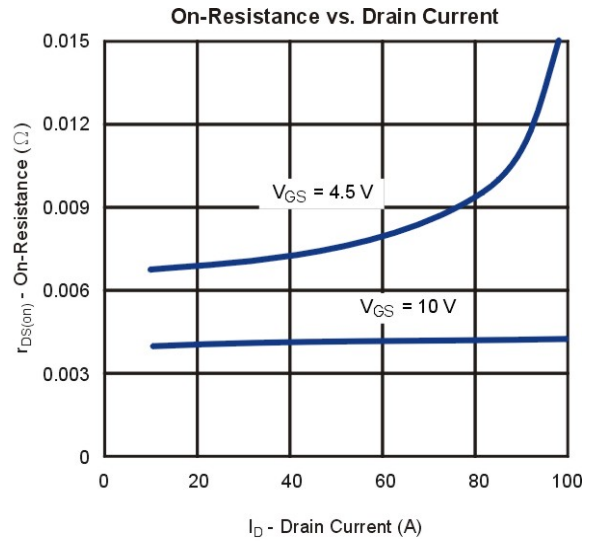
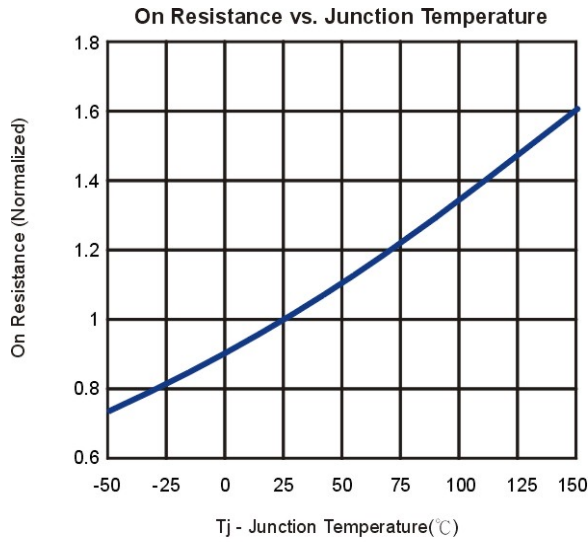
 Note: a. Pulse test: pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$

b. Matsuki Electric/ Force mos reserves the right to improve product design, functions and reliability without notice.



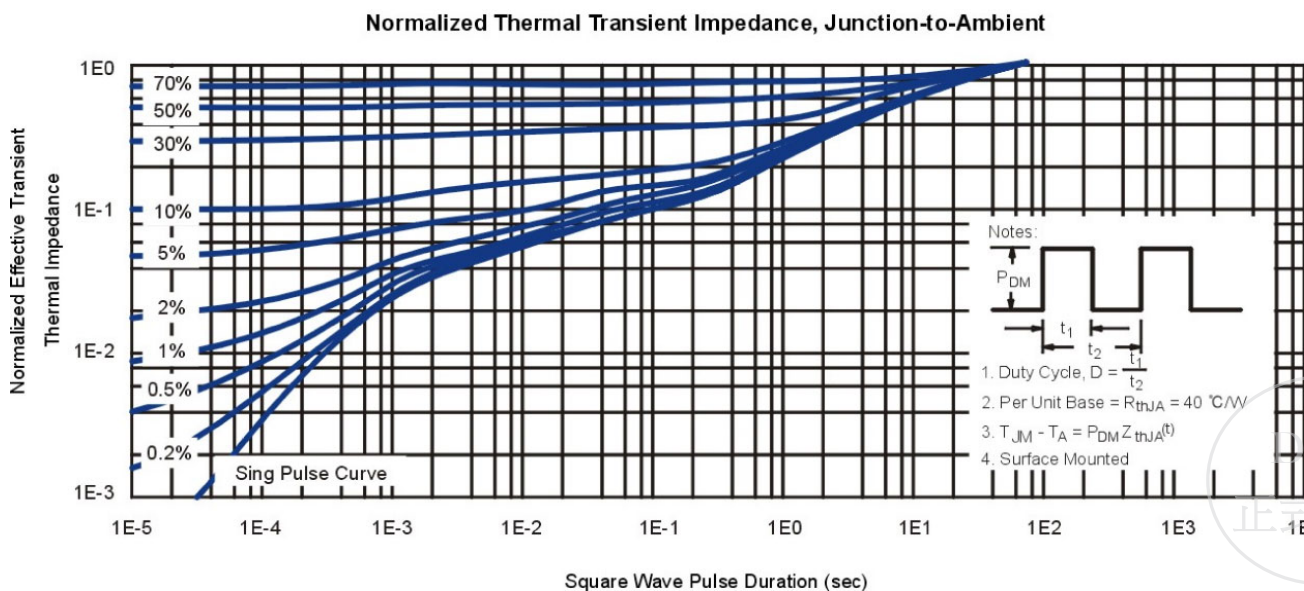
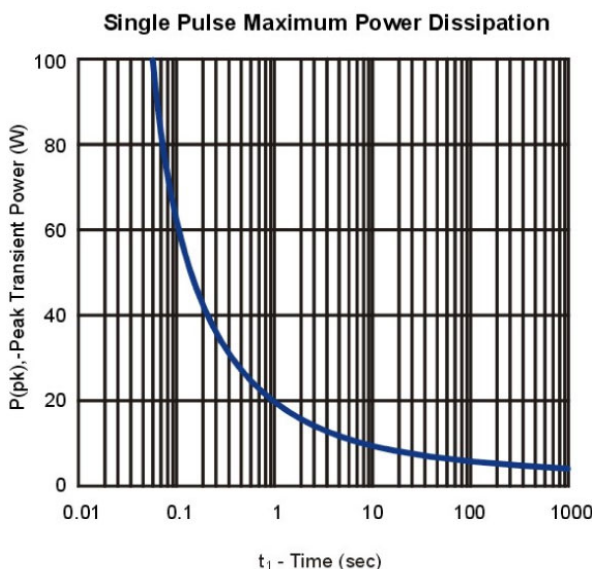
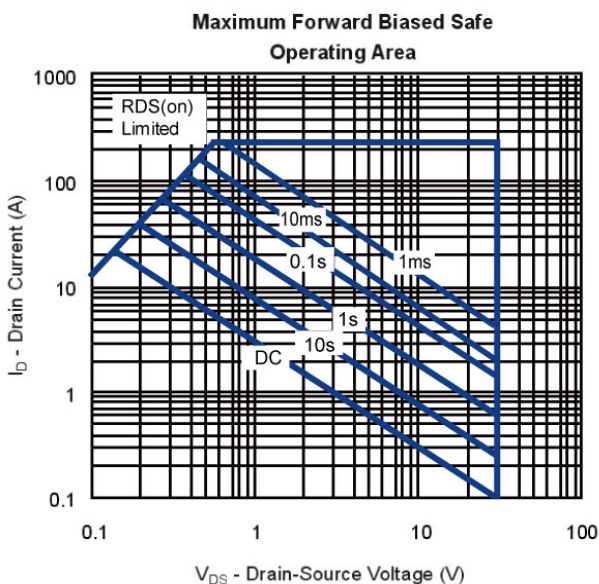
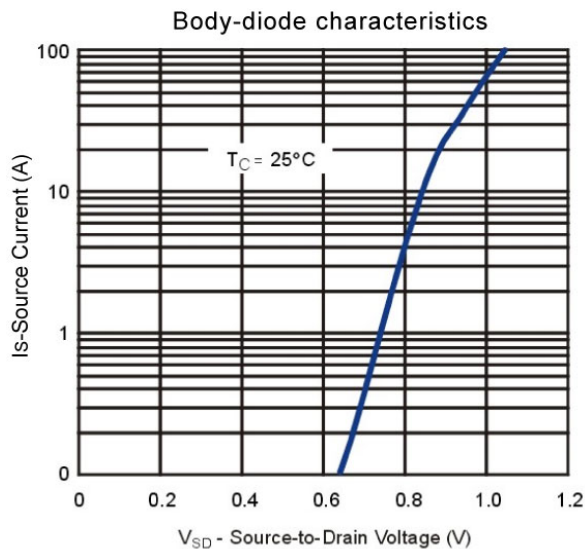
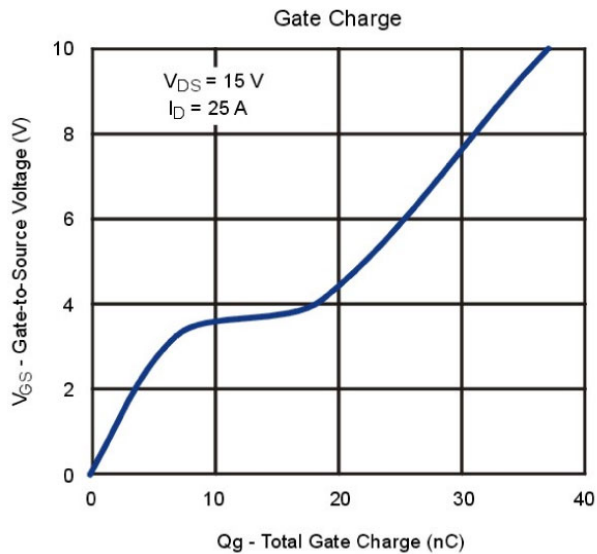
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Typical Characteristics (T_J = 25°C Noted)

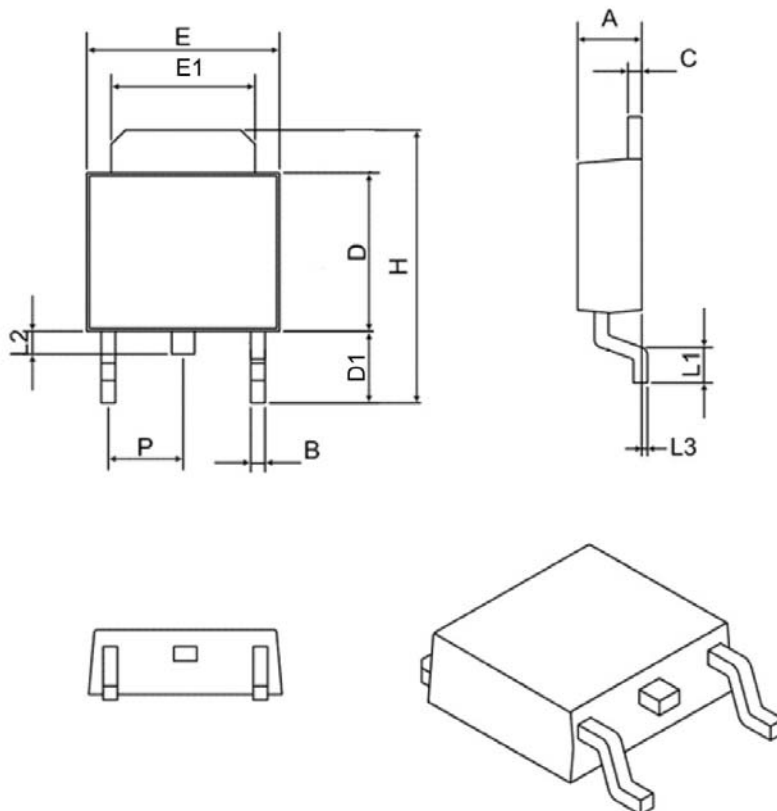


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TO-252 Package Outline



SYMBOL	MIN	MAX
A	2.10	2.50
B	0.40	0.90
C	0.40	0.90
D	5.30	6.30
D1	2.20	2.90
E	6.30	6.75
E1	4.80	5.50
L1	0.90	1.80
L2	0.50	1.10
L3	0.00	0.20
H	8.90	10.40
P	2.30 BSC	

DCC
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